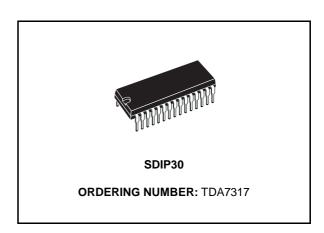


FIVE BANDS DIGITAL CONTROLLED GRAPHIC EQUALIZER

- VOLUME CONTROL IN 0.375dB STEP
- FIVE BANDS STEREO GRAPHIC EQUAL-IZER
- CENTER FREQUENCY, BANDWIDTH, MAX BOOST/CUT DEFINED BY EXTERNAL COMPONENTS
- ±14dB CUT/BOOST CONTROL IN 2dB/STEP
- ALL FUNCTIONS PROGRAMMABLE VIA SE-RIAL BUS
- VERY LOW DISTORTION
- VERY LOW NOISE AND DC STEPPING BY USE OF A MIXED BIPOLAR/CMOS TECH-NOLOGY

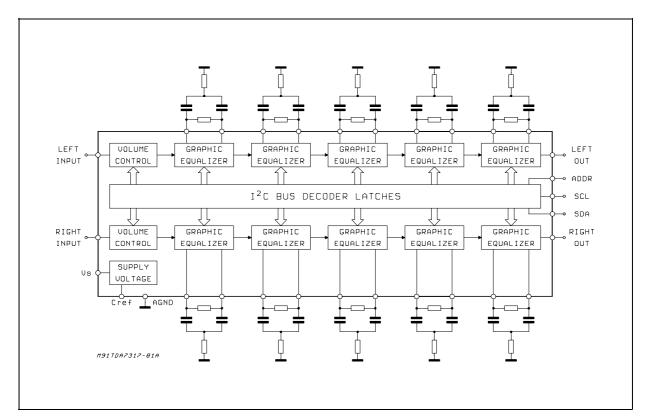
DESCRIPTION

The TDA7317 is a monolithic, digitally controlled graphic equalizer realized in BiCMOS mixed technology. The stereo signal, before any filtering, can be at-



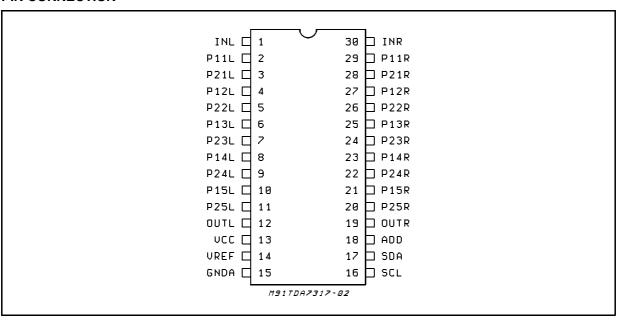
tenuated up to -17.625dB in 0.375dB step. All the functions can be programmed via serial bus making easy to build a μP controlled system. Signal path is designed for very low noise and distortion.

BLOCK DIAGRAM



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PIN CONNECTION



ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
Vs	Supply Voltage	10.2	V
Top	Operating Temperature Range	-40 to +85	°C
T_{stg}	Storage Temperature Range	-55 to +150	°C
R _{tjvins}	Thermal Resistance Junction pins max	85	°C/W

ELECTRICAL CHARACTERISTICS ($T_{amb} = 25^{\circ}C$, $V_{S} = 9V$, $R_{L} = 10K\Omega$, $R_{g} = 600\Omega$, f = 1KHz $V_{IN} = 1Vrms$, all controls in flat position (AV = 0dB) unless otherwise specified).

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Unit
SUPPLY						
Vs	Supply Voltage		6	9	10	V
I _S	Supply Current		8	14	20	mA
SVR	Ripple Rejection	f = 300Hz to 10KHz	60	80		dB

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ELECTRICAL CHARACTERISTICS (continued)

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Unit
NPUT						
R _I	Input Resistance		20	30	40	ΚΩ
$V_{\text{IN max}}$	Max Input Signal	THD = 0.3%	2	2.5		V_{RMS}
INS	Input Separation (1)		80	100		dB
OLUME C	ONTROL					
Crange	Control Range			17.625		dB
A _{VMIN}	Min. Attenuation		-0.5	0	0.5	dB
A _{VMAX}	Max. Attenuation		16.7	17.625	18.6	dB
ASTEP	Step Resolution		0.175	0.375	0.575	dB
E _A	Attenuation Set Error		-1		1	dB
E _T	Tracking Error				0.5	dB
V _{DC}	DC Steps	adjacent attenuation steps		0	3	mV
	QUALIZER	· ·	I			
THD	Distortion			0.01	0.1	%
Cs	Channel Separation		80	100		dB
e _{NO}	Output Noise	BW = 20Hz to 20KHz flat, AV = 0dB		8	20	μV
		A curve		6		μV
		BW = 20Hz to 20KHz AV = 0dB All bands = max. boost All bands = max. cut		24 6		μV μV
S/N	Signal to Noise Ratio	$A_V = 0$ dB; $V_{ref} = 1V_{RMS}$		100		dΒ
B _{step}	Step Resolution	Ay - Odb, V _{ref} - TVRMS	1	2	3	dB
	Control Range	max boost/cut	±12	±14	±16	dB
C _{RANGE} VDC	DC Steps	Adiacent Control Steps	<u> </u>	0.5	3	mV
AUDIO OUT	· · · · · · · · · · · · · · · · · · ·	Adiacent Control Steps		0.5	3	IIIV
	T	THD = 0.3%	2	2.5		V -
V _O	Output Voltage Output Load Resistance	THD = 0.3%		2.5		V _{RMS}
R _L			2		40	ΚΩ
C _L	Output Load Capacitance			40	10	nF
R _O	Output Resistance		5	10	20	Ω
V _{OUT} BUS INPUT	DC Voltage Level		4.2	4.5	4.8	V
	1				4	.,
V _{IL}	Input Low Voltage		-		1	V
V _{IH}	Input High Voltage		3	-		V
I _{IN}	Input Current		-5	-	+5	μΑ
Vo	Output Voltage SDA Acknowledge	I _O = 1.6mA			0.4	V
DDRESS I	PIN (Internal 50K Ω pull dow	n resistor)				
V_{IL}	Input Low Voltage				1	V
V_{IH}	Input High Voltage		V _{CC} -1V			V

NOTE: The input is grounded thru the 2.2 $\!\mu\text{P}$ capacitors



DEVICE DESCRIPTION

The TDA7317 is a five bands, digitally controlled stereo Graphic Equalizer.

The device is intended for high quality audio application in Hi-Fi, TV and car radio systems where feature like low noise and THD are key factors. A mixed Bipolar Cmos Technology allows:

Cmos analog switches for pop free commutations, high frequency op.amp. (GWB = 10MHz) and high linearity polisilicon resistor for THD = 0.01 (at Vin = 1Vrms) and a S/N ratio of 102dB. The internal Block Diagram is shown on page 1.

The first stage is a volume control. The control range is 0 to -17.625dB with 0.375dBstep.

The very high resolution (0.375dB step) allows the implementation of closed loop amplitude control system completely free from any acustical effect (stepping variation and pumping effect).

The volume control is followed by a serial five bands equalizer. Each filtering cell is the biquad cell shown in fig. 1

The internal resistor string is fixing the boost/cut value while the buffer makes the Q (quality factor) and central frequency, set by external components, fully indipendent from the internal resistors. Each filtering cell is realized using only 4 external components (2 capacitors and 2 resistors) allowing a flexible selection of centre frequency fo, Q factor and gain. Here below the basic formulae and the key features of each band pass filter are reported:

 f_0 = center frequency Gv = gain/loss at the center frequency f_0 Gv = 20log(Av)

$$Q = \frac{f_0}{f_2 - f_1}$$

where f_2 , $f_1 = 3dB$ Bandwidth limits.

$$A_{V} = \frac{(R2 \cdot C2) + (R2 \cdot C1) + (R1 \cdot C1)}{(R2 \cdot C1) + (R2 \cdot C2)}$$

$$Q = \frac{\sqrt{(R1 \cdot C1 \cdot R2 \cdot C2)}}{(R2 \cdot C1) + (R2 \cdot C2)}$$

$$f_o = \frac{1}{2\pi \cdot \sqrt{(R1 \cdot R2 \cdot C1 \cdot C2)}}$$

If C1 is fixed, then:

$$C2 = \frac{Q^2}{A_v - 1 - Q^2} \cdot C1$$

$$R2 = \frac{1}{2 \pi \cdot C1 \cdot f_0 \cdot \frac{(A_V - 1) \cdot Q}{(A_V - 1 - Q^2)}}$$

$$R1 = \frac{(A_v - 1)^2}{A_v - 1 - Q^2} \cdot R2$$

Likewise, the components'values can be determined by fixing one of the other three parameters. Referring to fig. 1 the suggested R2 value should be higher than $2K\Omega$ in order to have a good THD (internal op. amp. current limit).

Viceversa the R1 value should be equal or lower than 51K Ω in order to keep the "click"(DC step) very low.

A typical application is shown by fig. 2

Fig. 1

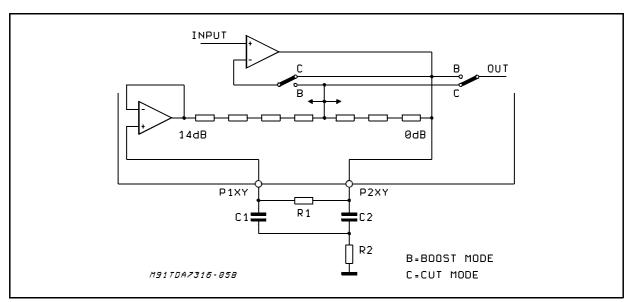
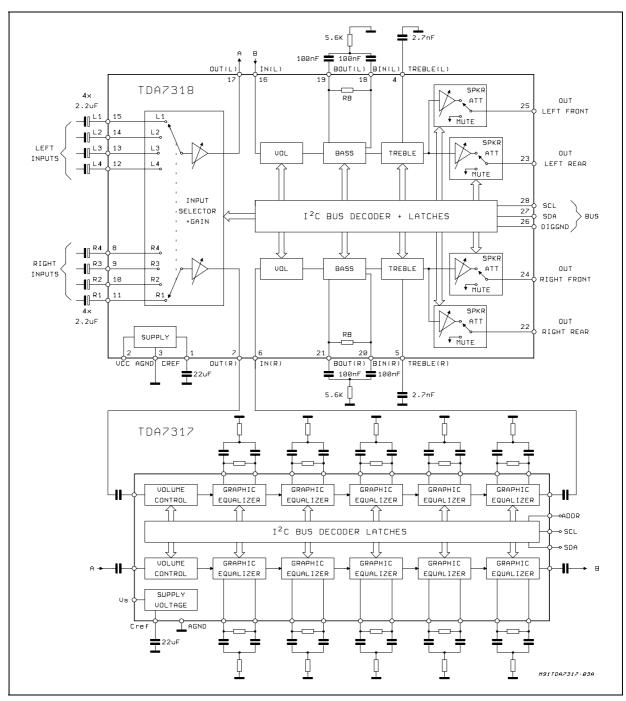


Figure 2: Application Circuit



The five bands graphic equalizer is used in conjunction with a TDA7318 (or another audioprocessor of the SGS-THOMSON 731X family).

The audioprocessor bass and treble tone can furnish two extra filter bands.

Application requiring higher number of external equalizer bands could be implemented by cascading 2 or more TDA7317 devices. In fact the

dedicated ADDR pin allows 2 addresses selection. Anyway, the address of the graphic equalizer is different from the audioprocessor one.

For example 11 bands are implemented by use of 2 TDA7317 plus an audioprocessor (TDA731X family).

In case one filtering cell is not needed, a short circuit must be provided between the P1xy and P2xy pins.

I²C BUS INTERFACE

Data transmission from microprocessor to the TDA7317 and viceversa takes place thru the 2 wires I²C BUS interface, consisting of the two lines SDA and SCL (pull-up resistors to positive supply voltage must be externally connected).

Data Validity

As shown in fig. 3, the data on the SDA line must be stable during the high period of the clock. The HIGH and LOW state of the data line can only change when the clock signal on the SCL line is LOW.

Start and Stop Conditions

As shown in fig.4 a start condition is a HIGH to LOW transition of the SDA line while SCL is HIGH. The stop condition is a LOW to HIGH transition of the SDA line while SCL is HIGH.

Byte Format

Every byte transferred to the SDA line must contain 8 bits. Each byte must be followed by an acknowledge bit. The MSB is transferred first.

Figure 3: Data Validity on the I²CBUS

Acknowledge

The master (μ P) puts a resistive HIGH level on the SDA line during the acknowledge clock pulse (see fig. 5). The peripheral (audioprocessor) that acknowledges has to pull-down (LOW) the SDA line during the acknowledge clock pulse, so that the SDA line is stable LOW during this clock pulse.

The audioprocessor which has been addressed has to generate an acknowledge after the reception of each byte, otherwise the SDA line remains at the HIGH level during the ninth clock pulse time. In this case the master transmitter can generate the STOP information in order to abort the transfer.

Transmission without Acknowledge

Avoiding to detect the acknowledge of the audio-processor, the μP can use a simplier transmission: simply it generates the 9th clock pulse without checking the slave acknowledging, and then sends the new data.

This approach of course is less protected from misworking and decreases the noise immunity.

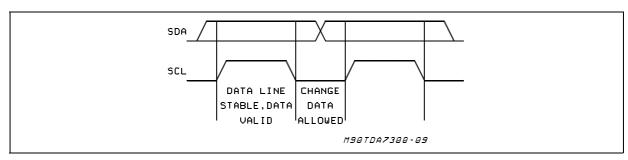


Figure 4: Timing Diagram of I²CBUS

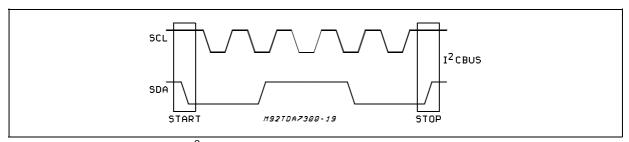
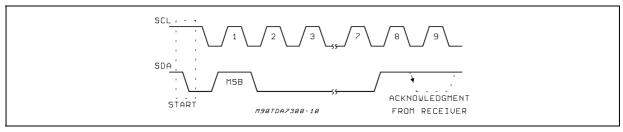


Figure 5: Acknowledge on the I²CBUS



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SOFTWARE SPECIFICATION

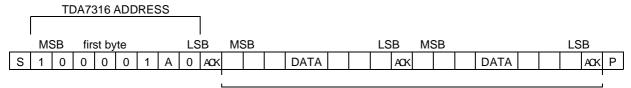
Interface Protocol

The interface protocol comprises:

- A start condition (s)
- A chip address byte, containing the TDA7317

address (the 8th bit of the byte must be 0). The TDA7317 must always acknowledge at the end of each transmitted byte.

- A sequence of data (N-bytes + acknowledge)
- A stop condition (P)



Data Transferred (N-bytes + Acknowledge)

ACK = Acknowledge

S = Start

P = Stop

MAX CLOCK SPEED 100kbits/s

SOFTWARE SPECIFICATION

Chip address (84 or 86 Hex)

1	0	0	0	0	1	Α	0
MSB							LSB

A = Logic level on pin ADDR

A = 1 if ADDR pin = open

A = 0 if ADDR pin = connected to ground

SOFTWARE SPECIFICATION (continued)

DATA BYTES (detailed description)

Volume

MSB							LSB	FUNCTION
0	Χ	B2	B1	В0	A2	A1	A0	Volume 0.375dB steps
					0	0	0	0
					0	0	1	-0.375
					0	1	0	-0.75
					0	1	1	-1.125
					1	0	0	-1.5
					1	0	1	-1.875
					1	1	0	-2.25
					1	1	1	-2.625
0	Χ	B2	B1	В0	A2	A1	A0	Volume -3dB steps
		0	0	0				0
		0	0	1				-3
		0	1	0				-6
		0	1	1				-9
		1	0	0				-12
		1	0	1				-15

Graphic Equalizer

MSB							LSB	FUNCTION
1	D3	D2	D1	D0	S2	C1	C0	
	0 0 0 0 1	0 0 1 1 0	0 1 0 1 0					Band 1 Band 2 Band 3 Band 4 Band 5
	D3 D3	D2 D2	D1 D1	1 0	C2 C2	C1 C1	C0	cut Boost
					0 0 0 0 1 1 1	0 0 1 1 0 0	0 1 0 1 0 1 0	0dB 2dB 4dB 6dB 8dB 10dB 12dB 14dB

AX = 0.375dB steps, BX = 3dB steps, CX = 2dB steps, X = dont'care

STATUS AFTER POWER-ON RESET						
Volume	-17.25dB					
Graphic equalizer bands	-12dB					

APPLICATION INFORMATION

A typical application is indicated in figure 4, while

the P.C. Board and components layout are reported in figure 5. The external components, are calculated for 2 different max boost/cut conditions

TABLE 1: Max Boost/cut = 20 dB (each cell = ± 14 dB)

	F (HZ)	Q	R1 (K Ω)	R2 (K Ω)	C1 (nF)	C2 (nF)	Av max (dB)
BAND 1	10363.38	1.49	47	5.1	0.820	1.2	13.52
BAND 2	261.03	1.49	47	5.1	33	47	13.63
BAND 3	1036.34	1.49	47	5.1	8.2	12	13.52
BAND 4	3168.08	1.49	47	5.1	2.7	3.9	13.57
BAND 5	59.75	1.11	43	7.5	220	100	13.88

For THD performance the sequence Band 1, 2, 3, 4, 5, is recommended

TABLE2: Max Boost/cut = 17dB (each cell = \pm 12dB)

	F (HZ)	Q	R1 (KΩ)	R2 (K Ω)	C1 (nF)	C2 (nF)	Av max (dB)
BAND 1	10158.00	1.15	33	6.2	1.2	1	11.83
BAND 2	250.81	1.21	30	5.1	47	56	11.33
BAND 3	977.34	1.20	39	6.8	10	10	11.75
BAND 4	3429.00	1.25	39	6.2	2.7	3.3	11.67
BAND 5	61.82	1.15	33	6.2	180	180	11.27

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Figure 4

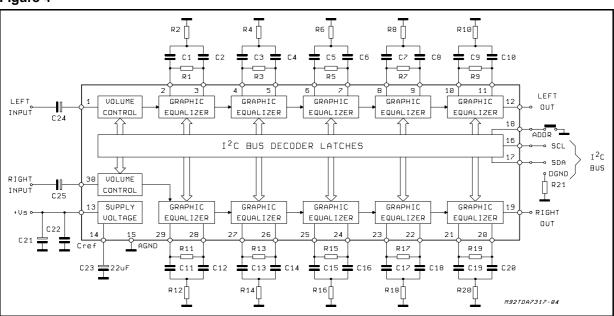
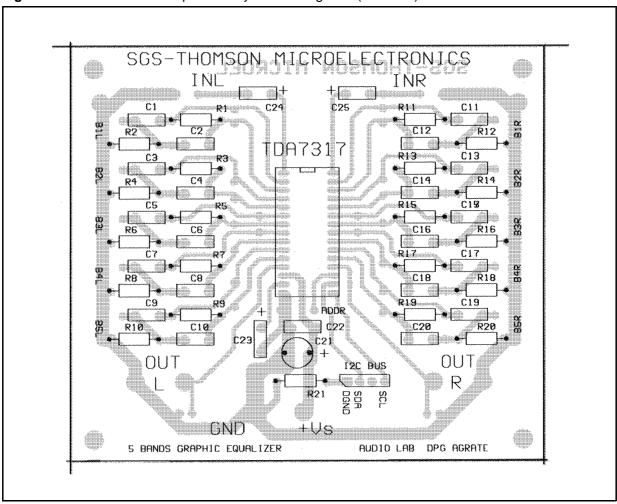


Figure 5: PCP Board and components layout of the figure 4 (scale 1:1)



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Measurements done on the test jig of fig. 5 using the components indicated in table2, are reported

Figure 6: Frequency Response

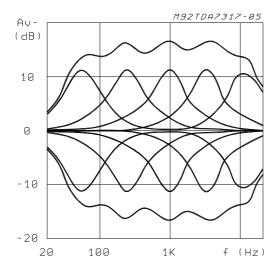
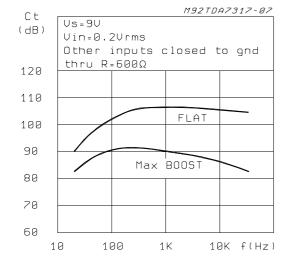
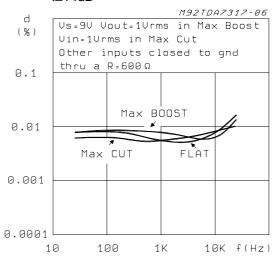


Figure 8: Cross Talk vs Frequency



in figg. 6, 7,8.

Figure 7 THD vs Frequency Max Boost/cut = :±14dB

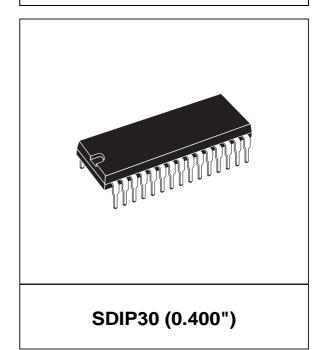


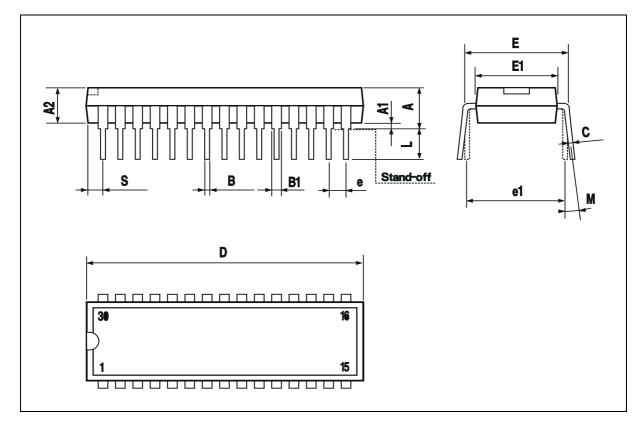
Purchase of I^2C Components of SGS-THOMSON Microlectronics, conveys a license under the Philips I^2C Patent Rights to use these components in an I^2C system, provided that the system conforms to the I^2C Standard Specifications as defined by Philips.

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DIM.		mm		inch				
Diiii.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.		
А			5.08			0.20		
A1	0.51			0.020				
A2	3.05	3.81	4.57	0.12	0.15	0.18		
В	0.36	0.46	0.56	0.014	0.018	0.022		
B1	0.76	0.99	1.40	0.030	0.039	0.055		
С	0.20	0.25	0.36	0.008	0.01	0.014		
D	27.43	27.94	28.45	1.08	1.10	1.12		
Е	10.16	10.41	11.05	0.400	0.410	0.435		
E1	8.38	8.64	9.40	0.330	0.340	0.370		
е		1.778			0.070			
e1		10.16			0.400			
L	2.54	3.30	3.81	0.10	0.13	0.15		
М	0°(min.), 15°(max.)							
S	0.31			0.012				

OUTLINE AND MECHANICAL DATA





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